

IN THE SPECIFICATION:

Please amend paragraph [0006] as follows:

[0006] The CMP apparatus of FIG. 1A also includes a rotatable substrate carrier 18 configured to hold a semiconductor substrate 20 (such as, by way of example, a silicon wafer) bearing a material layer 25 to be polished. The substrate carrier 18 exerts a downward force, indicated by arrow 22, normal to the surface 24 of the material layer 25 to be polished, creating a pressure between the surface 24 of the material layer 25 to be polished and the polishing surface 26 of the polishing pad 14. The rotatable substrate carrier 18 may be designed to exert varying amounts of force against the semiconductor substrate 20 and may utilize various, ~~well-known~~ well-known technologies, such as mechanical affixation, vacuum affixation, frictional affixation, or any other suitable technique, to hold the semiconductor substrate 20 in place during polishing.

Please amend paragraph [0010] as follows:

[0010] The effect of CMP is illustrated in FIGs. 2 through 4. Each of these figures ~~illustrate~~ illustrates an incomplete semiconductor device 44 before or after undergoing CMP. However, the application of CMP processes is not limited to incomplete semiconductor devices having the characteristics illustrated in FIGs. 2 through 4. As is well-known by those of ordinary skill in the art, CMP processes may be applied to a wide range of semiconductor devices at various stages of fabrication. Moreover, as is also well-known, CMP process parameters are variable, depending on the desired result and the characteristics of the substrate being polished. The structures and results depicted in FIGs. 2 through 4 are therefore provided for illustrative purposes only.

Please amend paragraph [0029] as follows:

[0029] FIG. 2 provides a schematic representation of a ~~cross section~~ cross-section of a portion of an intermediate semiconductor device formed on a semiconductor substrate, such as a wafer.

Please amend paragraph [0032] as follows:

[0032] FIG. 5 provides a schematic depiction of a ~~cross-section~~ cross-section of a portion of a polishing table useful for CMP and having a first embodiment of the deformable pad of the present invention attached thereto.

Please amend paragraph [0033] as follows:

[0033] FIG. 6 provides a schematic illustration of a ~~cross-section~~ cross-section of a portion of a polishing table useful for CMP having a carrier film, a first embodiment of the deformable pad of the present invention, and a polishing pad attached thereto.

Please amend paragraph [0034] as follows:

[0034] FIG. 7 provides a schematic illustration of a ~~cross-section~~ cross-section of a portion of a polishing table useful for CMP having a deformable pad according to a second embodiment of the deformable pad of the present invention attached thereto.

Please amend paragraph [0036] as follows:

[0036] FIG. 9 provides a schematic illustration of a ~~cross-section~~ cross-section of a portion of a polishing table useful for CMP processing having a deformable pad according to a third embodiment of the deformable pad of the present invention attached thereto.

Please amend paragraph [0038] as follows:

[0038] FIG. 11 provides a schematic illustration of a ~~cross-section~~ cross-section of a portion of a polishing table useful for CMP processing having a deformable pad according to a fourth embodiment of the deformable pad of the present invention attached thereto.

Please amend paragraph [0051] as follows:

[0051] A portion of a CMP apparatus having a first embodiment of the deformable pad of the present invention attached thereto is illustrated in FIG. 5. In the first embodiment, the top surface and bottom surface of the deformable pad 70 are discontinuous. In such an embodiment, the deformable pad of the present invention includes only a plurality of solid supports 76, with the top surfaces 78 of the solid supports 76 forming the discontinuous top surface 72 of the deformable pad 70 and the bottom surfaces 80 of the solid supports 76 forming the discontinuous bottom surface 74 of the deformable pad 70. Where the deformable pad 70 of the present invention includes only a plurality of solid supports 76, the top surfaces 78 of the solid supports 76 forming the discontinuous top surface 72 of the deformable pad 70 are attached directly to the lower surface 82 of a polishing pad 84 by means known in the art, such as ~~double-sided~~ double-sided tape or, preferably, pressure sensitive adhesive, and the bottom surfaces 80 of the plurality of solid supports 76 forming the discontinuous bottom surface 74 of the deformable pad 70 are indirectly or directly attached to the upper surface 86 of a polishing table 88 using known attachment means such as those used to attach the discontinuous top surface 72 of the deformable pad 70 to the lower surface 82 of the polishing pad 84.